



HPC@Intel: On Driving Industrial Innovation

Dr. Stephen Wheat
General Manager, HPC
Intel Corp.



Agenda

To Compete You Must Compute

**Neo-heterogeneity: The Future of Technical
Computing Hardware**

The Imperative: Modernizing Code

Agenda

To Compete You Must Compute

**Neo-heterogeneity: The Future of Technical
Computing Hardware**

The Imperative: Modernizing Code

Dated, but still very relevant story to explain HPC

Why HPC in multimedia form

Technical Computing Continues Its Rapid Growth

To Compete, You Must Compute

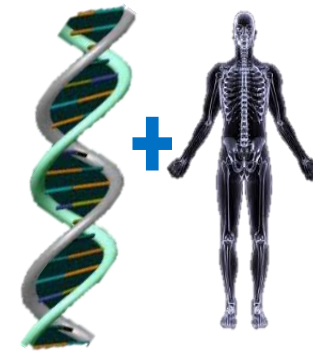
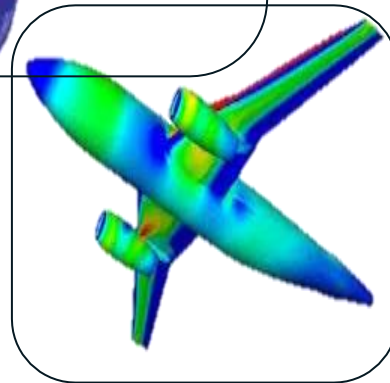
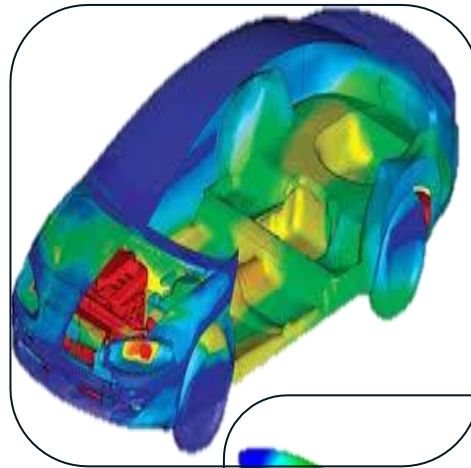
Governments & Research

Commercial/Industrial

New Users – New Uses



The Human Brain Project
<http://www.humanbrainproject.eu/>
Budget: Euro 1 Billion



Genomics + Clinical Information

*From
Diagnosis to
personalized
treatments
quickly*

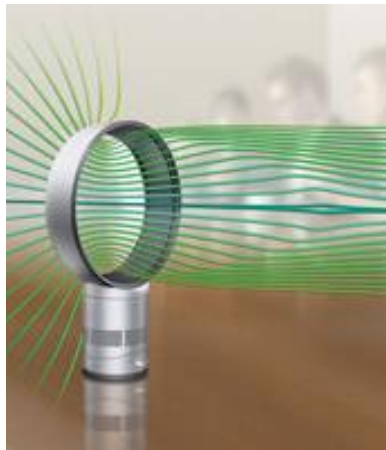
Dyson Creates a Revolutionary Fan

Utilizing new scientific method

Reduced the number of costly, time-consuming physical prototypes

2.5x better fan performance while eliminating external moving parts

By investigating 10x the number of design possibilities using virtual prototyping



Virtual prototype

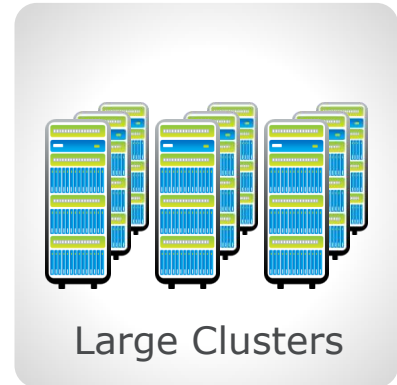
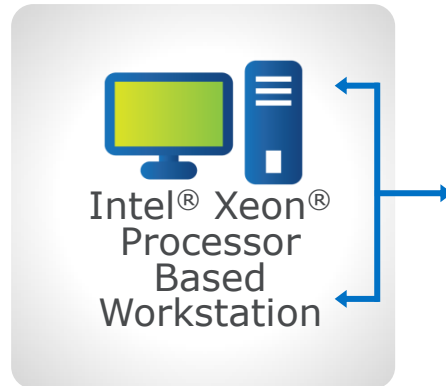


Dyson Air Multiplier Fan

Source: Ansys Advantage Volume IV, Issue 2 2010 pp. 5-7
© Ansys Corp.

The Right Tool for the Job: A Continuum of Computing

How do you get breakthroughs for your investment



**Common underlying architecture
scales investments across technical computing platforms**

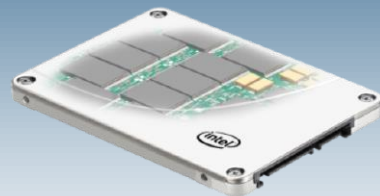
Building the Right Tool for the Job

Balanced compute, storage, and interconnects based on workload

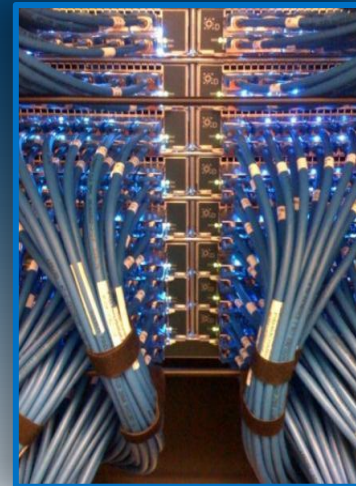
COMPUTE



STORAGE



NETWORKING



SOFTWARE



Audi Workflow

Real-time, photo-realistic predictive rendering

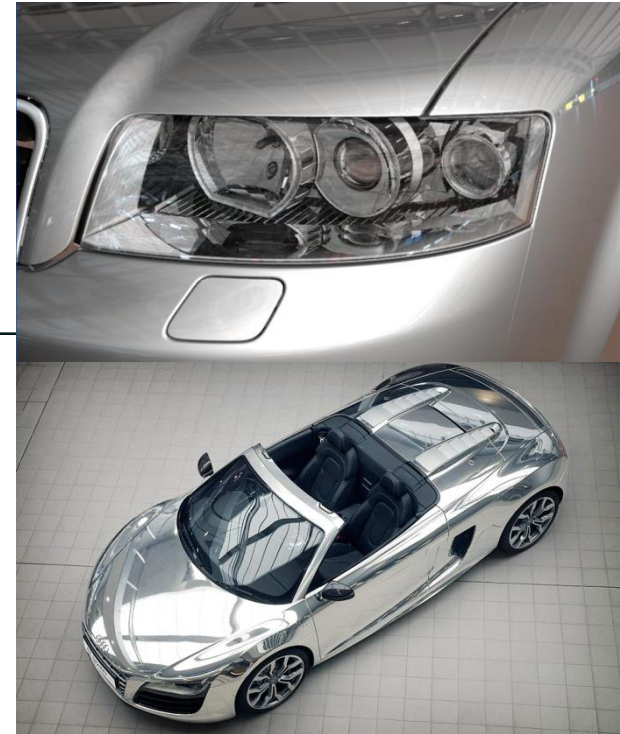


Topline
Innovation

More compelling, accurate
visualization of car design

Avoid physical prototyping
spin by identifying body part
fit issues

Reduce turn-around from
identifying design changes



Virtual prototyped images



Bottom-line
Costs

Get the most for their Autodesk
software investment with
optimized performance on Intel
platforms

Intel® Xeon® Processor E5-
2600 product family based
solution across workstations
and clusters reduced
deployment and maintenance
costs

Images courtesy of The Audi Group, Used by permission

Audi Results

Better, safer cars to market quicker

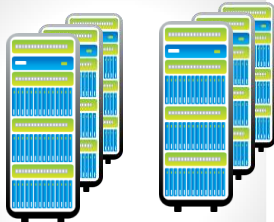


Upgraded 2000 workstations to latest Intel® Xeon® processor E5-2600 product family



Local Cluster Computation

Phase 1: 450 dual-processor nodes. Phases 2 & 3 will duplicate 1,350 node visualization cluster



Large Cluster

Scaled Autodesk Opticore V13 on 1024 Intel® Xeon® processor E5-2600 product family



Result: Reduced physical prototypes

Images courtesy of The Audi Group, Used by permission

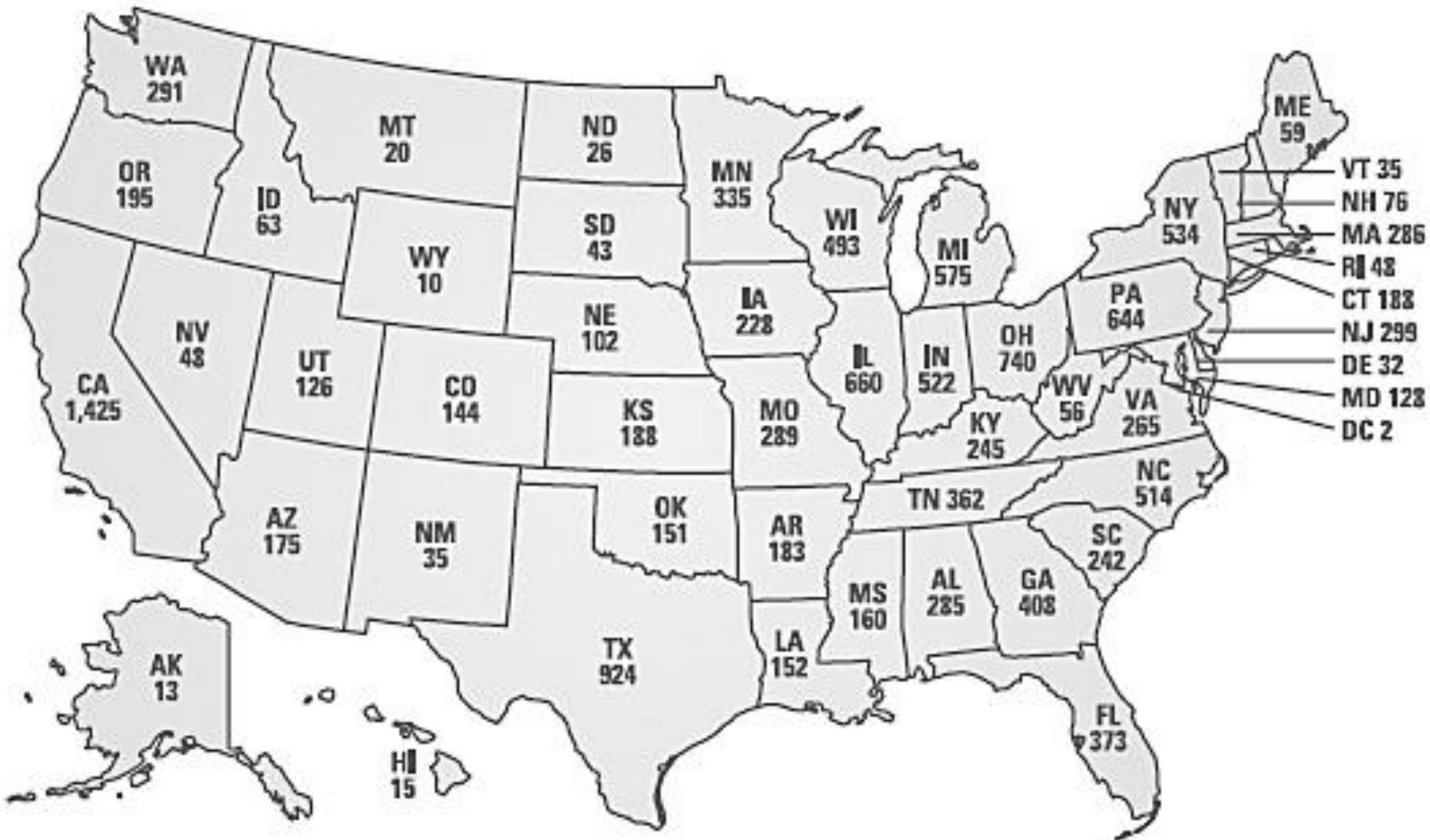
It's not just the Tier 1 OEMs

On the Missing Middle in Manufacturing

International update

Local update

Manufacturing Jobs in the USA (K)



Source: U.S. Bureau of Labor Statistics, 2008

And it's not just reaching the SMMs

An update on the Wheeling program

Making A New Reality Faster Than Ever

From Vision to Reality: Without Prototypes!



2000



2005



2010



2013

2013

Goal: Increase level of detail & reality and opportunity to experience a product before it is built

Goal: Reduction of physical cars needed for decision process > cost reduction, process speed up

"For Audi to stay on the forefront of automotive design, we required a new way to visualize our designs. Working with Intel and Autodesk, we have been able, **for the first time,** to adopt **Real Time Predictive Rendering** to interactively see our car design concepts with high fidelity visualization. This helps us reduce the costs of development by **eliminating expensive prototype turns**" -- Audi

What Makes a Great HPC Cluster?

Industry-leading workload performance

Intel® Xeon® processors:

Performance for highly-parallel workloads while preserving software investment

Intel® Xeon Phi™ coprocessors:



Fast, reliable access to data

Intel Xeon processor based storage

Intel® SSDs

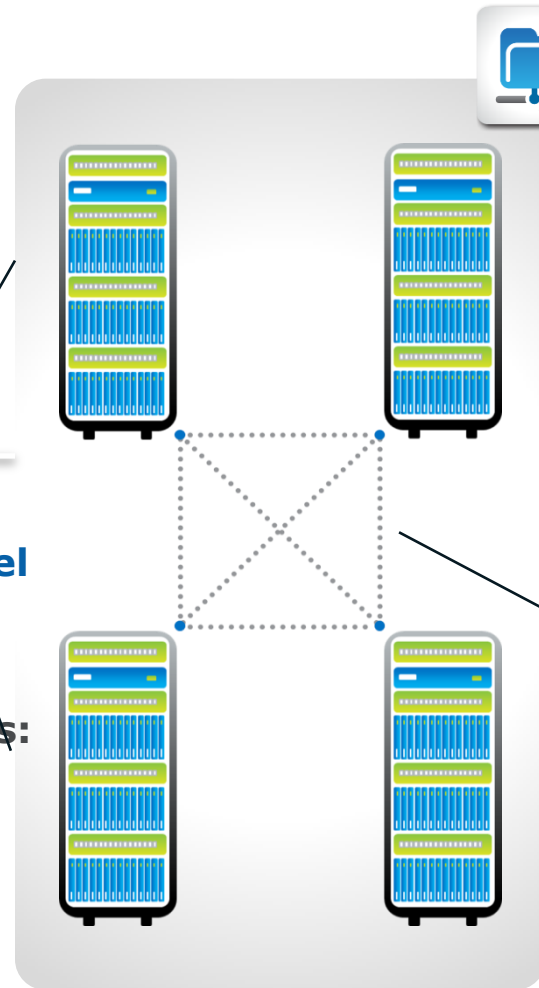
Intel® Enterprise Edition for Lustre* software

Fast, cost-effective data movement between nodes

Intel® True Scale fabric

Ease of deployment and maintenance

Intel® Cluster Ready



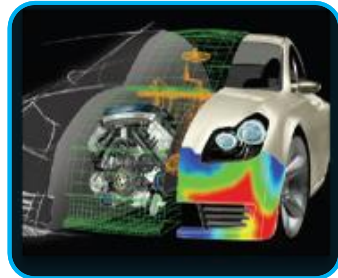
Intel: The Architecture for Discovery



Intel® Xeon® Processor E5-2600 V2 Family

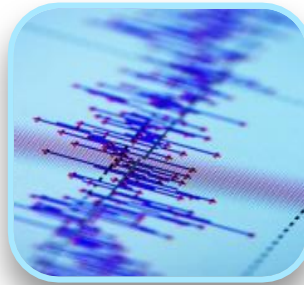
Expect average increase of 1.3x across real-world applications

CAD/CAE



UP TO
1.37x

Energy



UP TO
1.59x

Life Sciences



UP TO
1.38x

Finance



UP TO
1.32x

CAD/CAE Configuration (Ansys Fluent v14.0*):

2S IVB Romley-EP: E5-2697 v2 (2.7GHz CPU X 2 w/ 12 Cores), 64G Mem; OS: RHEL 6.4

2S SNB Romley-EP: E5-2690 (2.9GHz CPU X 2 w/ 8 Cores), 64G Mem; OS: RHEL 6.3

Energy Configuration (Paradigm® GeoDepth® v2011.3):

2S IVB Romley-EP: E5-2697 (2.7GHz CPU X 2 w/ 12 Cores), 64G 1867 Mem; OS: RHEL 6.4

2S SNB Romley-EP: E5-2670 (2.6GHz CPU X 2 w/ 8 Cores), 64G 1600 Mem; OS: RHEL 6.3

Life Sciences Configuration (PerkinElmer Acapella* v3.1.0):

2S IVB Romley-EP: 2.7GHz CPU X 2 w/ 12 Cores, 32G 1867 Mem; OS: Windows Server 2008 R2 with SP1 (x64)

2S SNB Romley-EP: 2.7GHz CPU X 2 w/ 8 Cores, 32G 1600 Mem; OS: Windows Server 2008 R2 with SP1 (x64)

Finance Configuration (SunGard Adaptiv* Benchmark X 13.1):

2S IVB Romley-EP: E5-2697 v2 (2.7GHz CPU X 2 w/ 12 Cores), 64G Mem; OS: Win Server 2008 R2

2S SNB Romley-EP: E5-2680 (2.7GHz CPU X 2 w/ 8 Cores), 64G Mem; OS: Win Server 2008 R2

Software and workloads used in performance tests may have been optimized for performance only on Intel microprocessors. Performance tests, such as SYSmark* and MobileMark*, are measured using specific computer systems, components, software, operations and functions. Any change to any of those factors may cause the results to vary. You should consult other information and benchmark tests to assist you in fully evaluating your contemplated purchases, including the performance of that product when combined with other products. NEX HEVC Encoder*

For more information go to <http://www.intel.com/performance>

Agenda

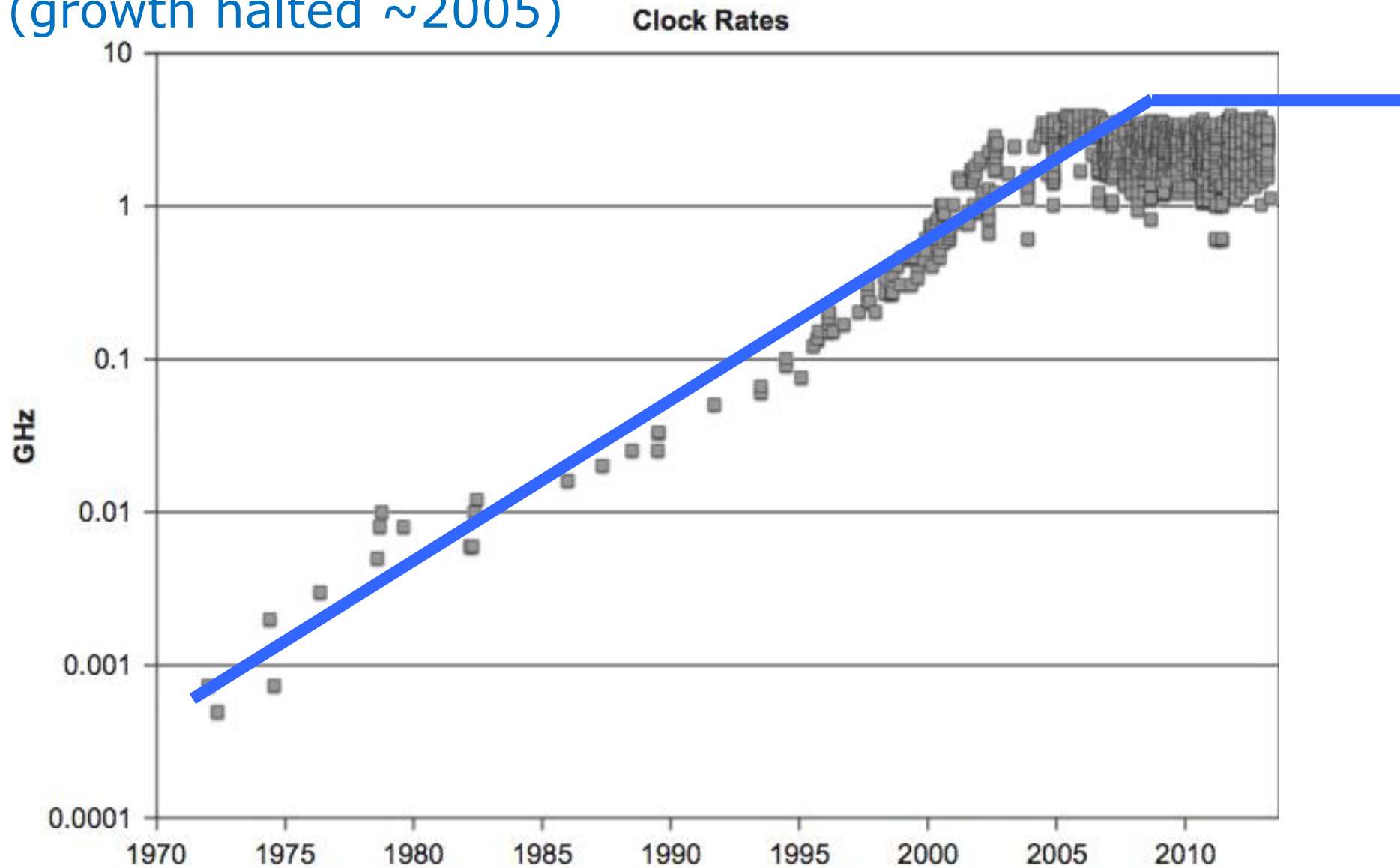
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Wrap up

Processor Clock Rate (growth halted ~2005)

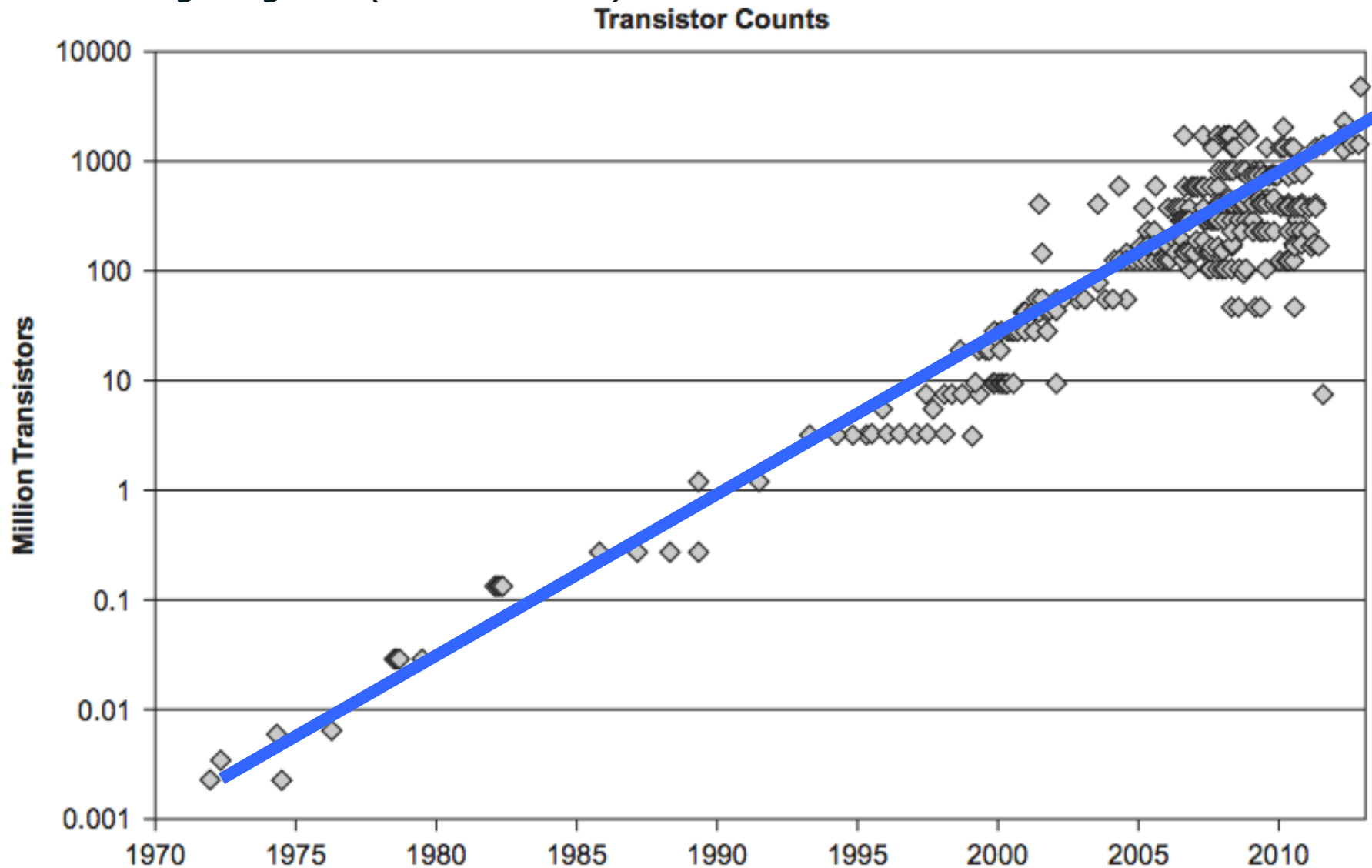


© 2013, James Reinders & Jim Jeffers, diagram used with permission



Transistors per Processor

Continuing to grow (Moore's Law)

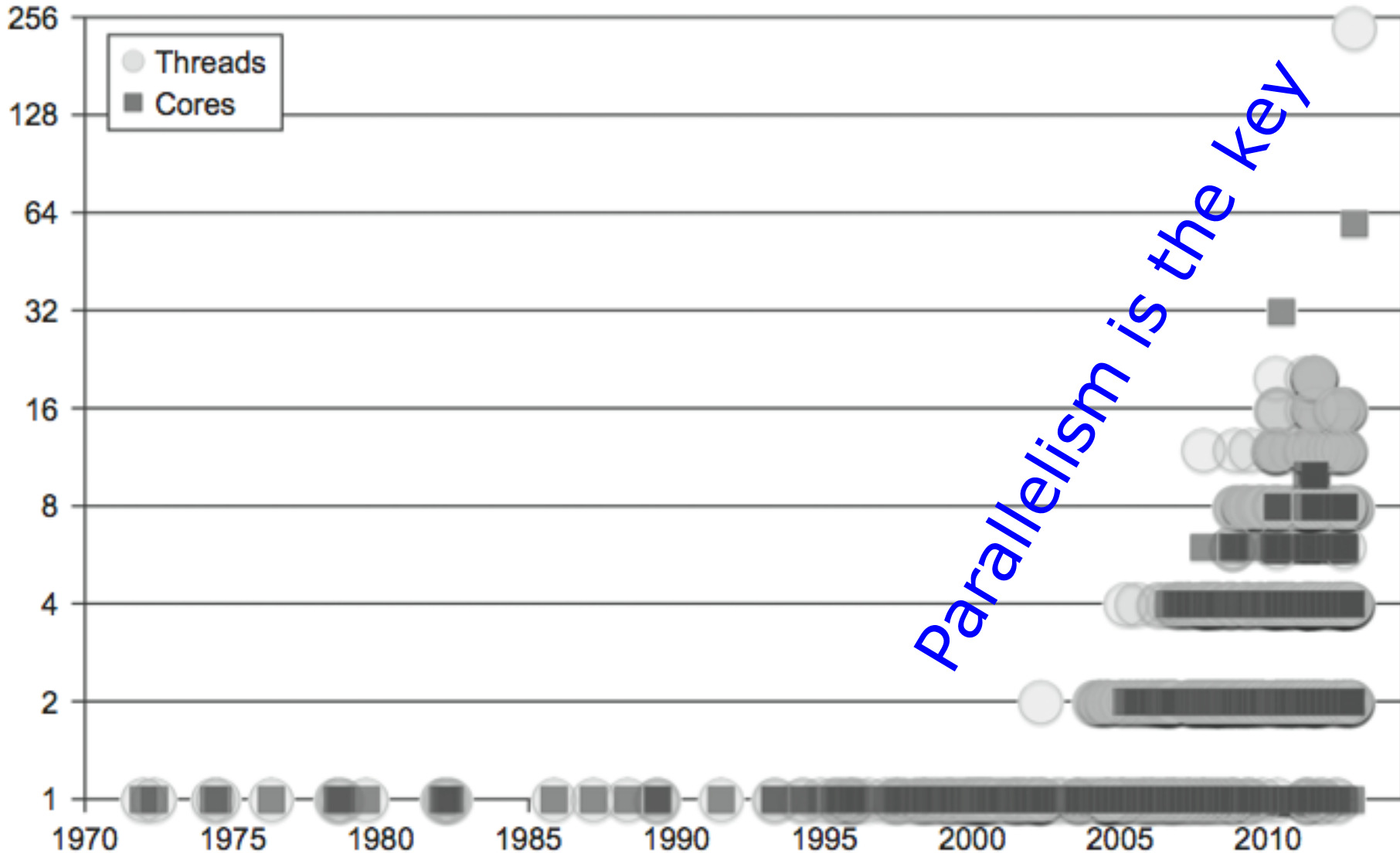


© 2013, James Reinders & Jim Jeffers, diagram used with permission

Thread and Core Count Growth

Parallel is the path forward

Core and Thread Counts



© 2013, James Reinders & Jim Jeffers, diagram used with permission

Two Types of Parallelism
for Programmers to Identify and Use

Scaling (more cores)

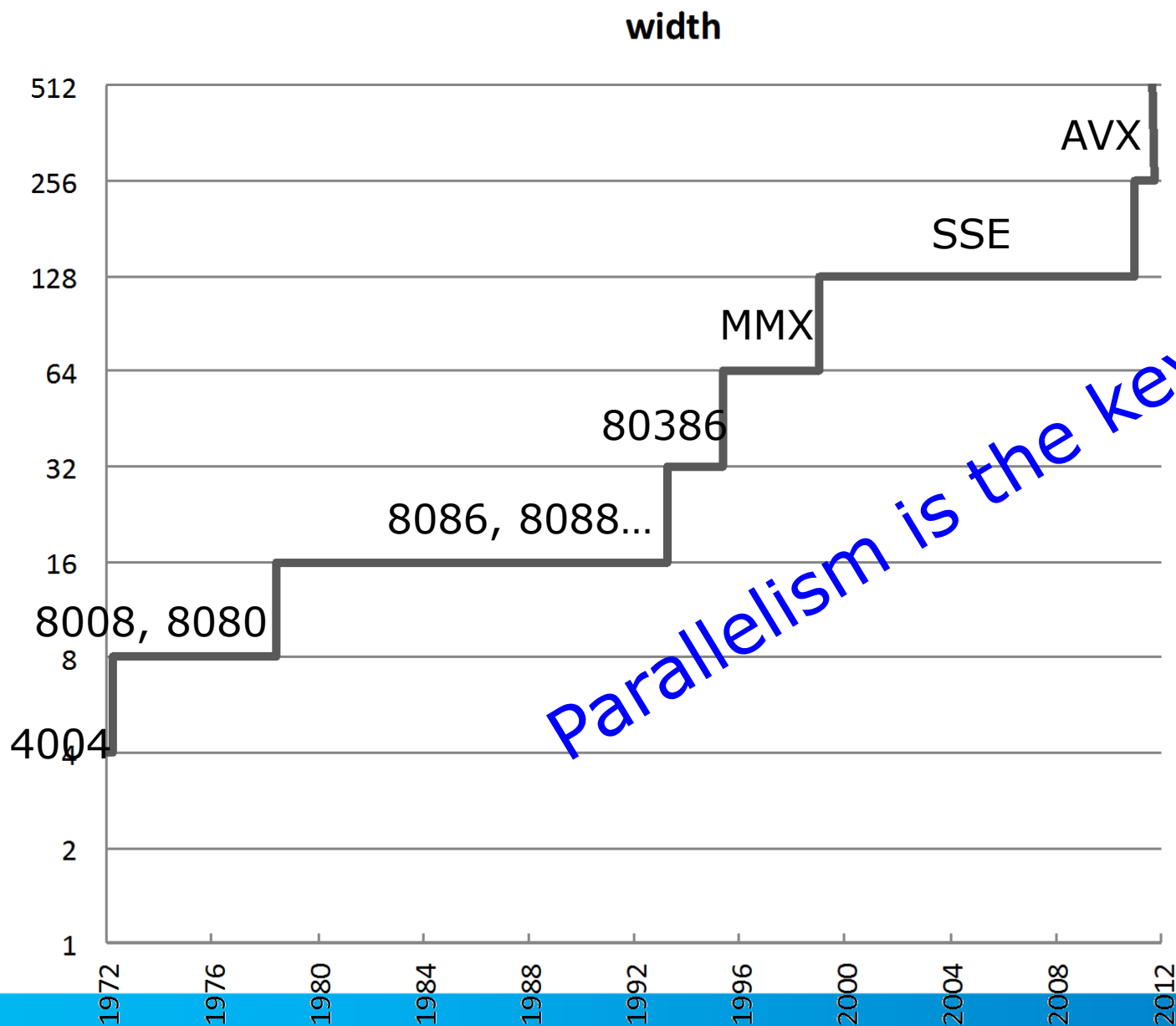
“Task parallelism”

Vectorization (wider vectors)

“Data parallelism”

Vector Growth

Parallel is the path forward



Parallelism is the key

Two Types of Parallelism
for Programmers to Identify and Use

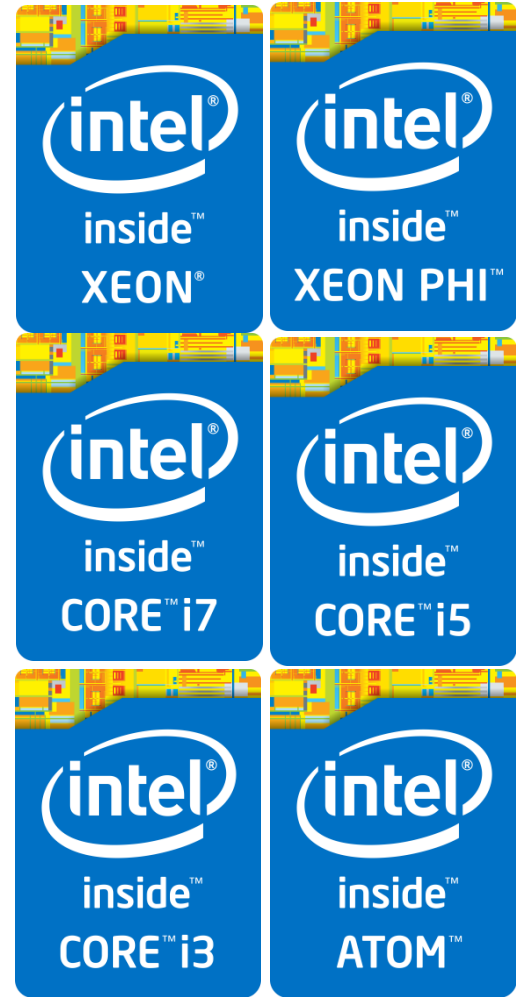
Scaling (more cores)
“Task parallelism”

Vectorization (wider vectors)
“Data parallelism”

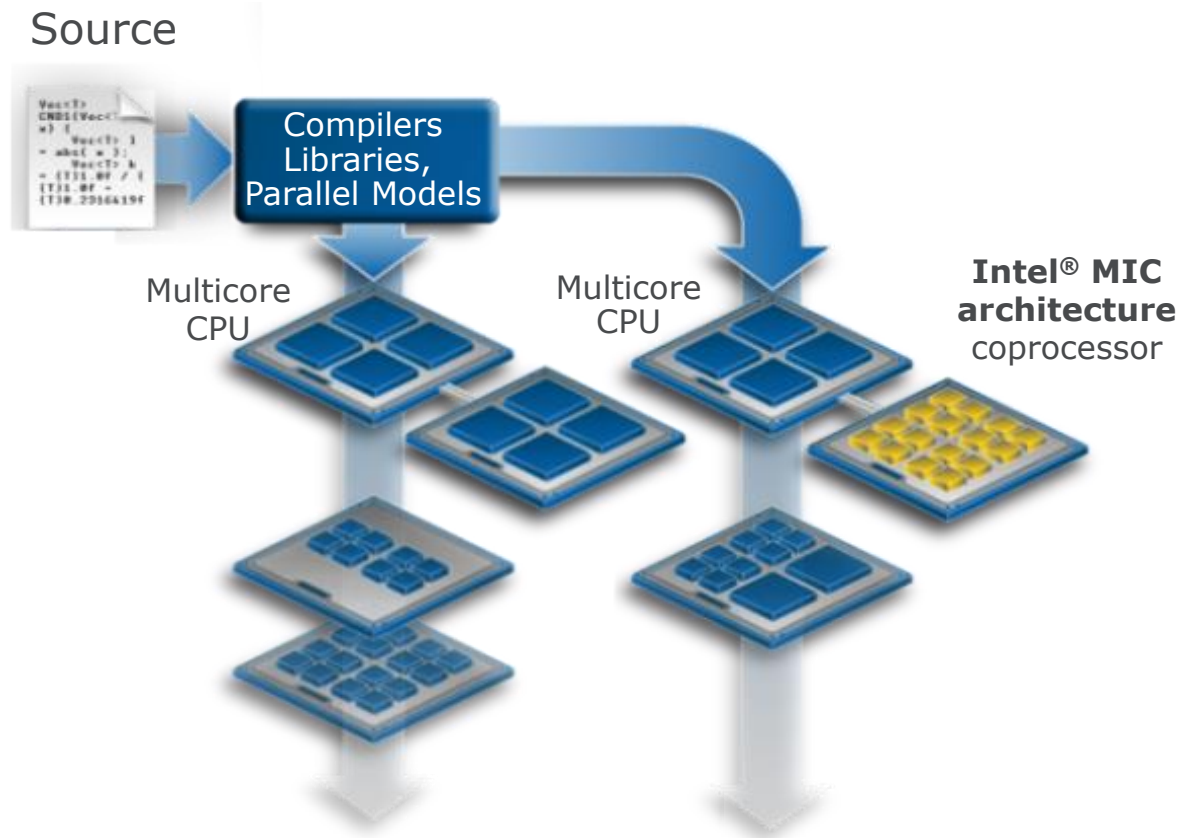
DATA LAYOUT / USAGE IS KEY

vision

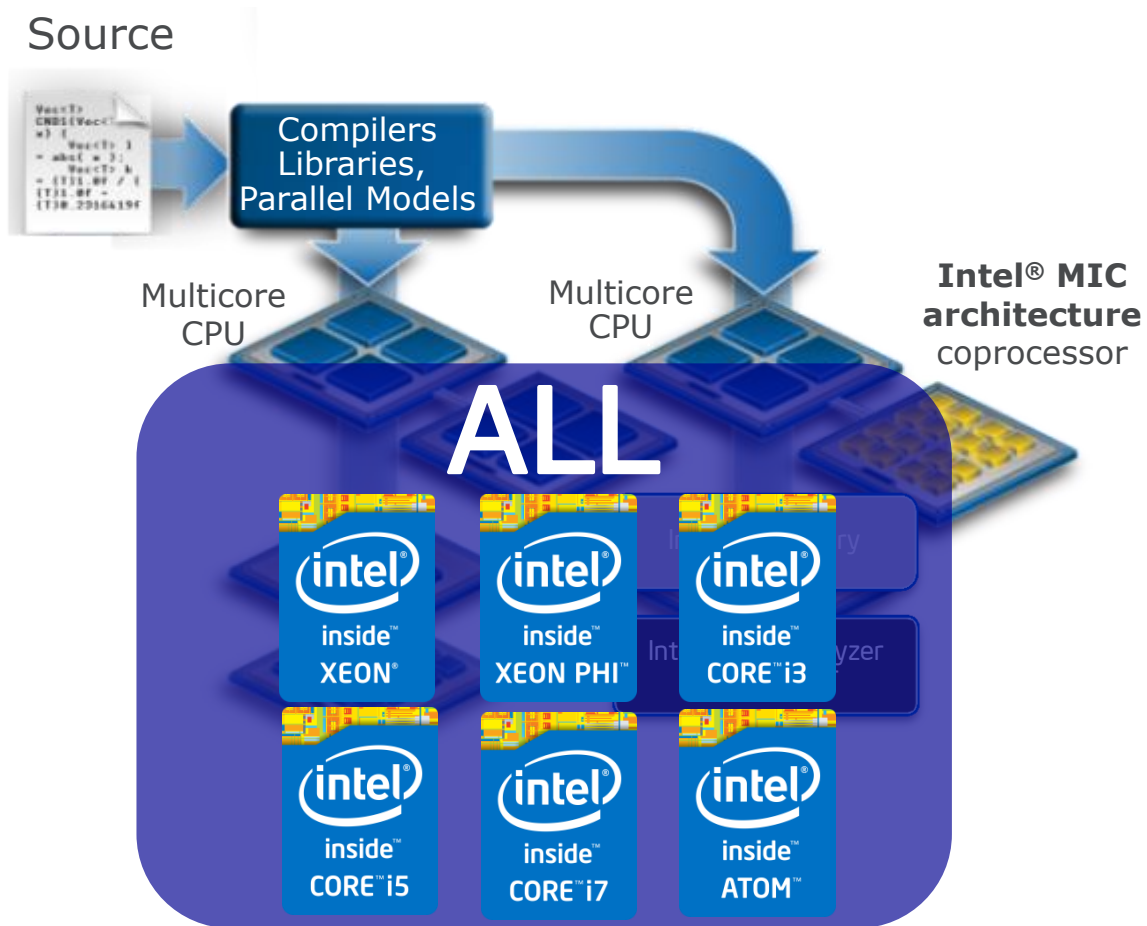
span from few
cores to many
cores with
consistent models,
languages, tools,
and techniques



The Heterogeneous Architecture



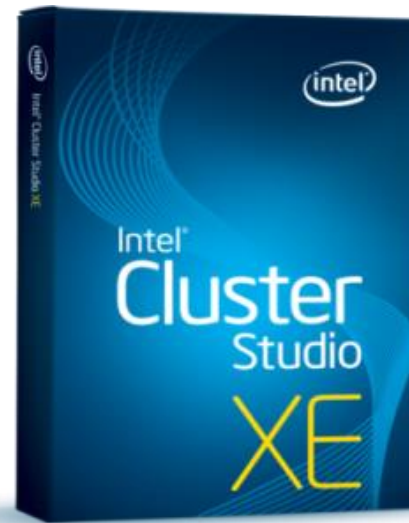
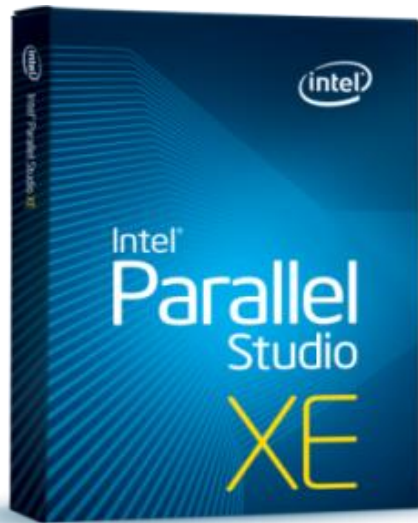
Neo-Heterogeneity – The Game Changer



“Unparalleled productivity... most of this software does not run on a GPU” – Robert Harrison, NICS, ORNL

R. Harrison, “Opportunities and Challenges Posed by Exascale Computing - ORNL's Plans and Perspectives”, National Institute of Computational Sciences, Nov 2011”

Tools to Maximize Application Performance



Intel® C/C++ and Fortran Compilers w/OpenMP

Intel® MKL, Intel® Cilk Plus, Intel® TBB, and Intel® IPP

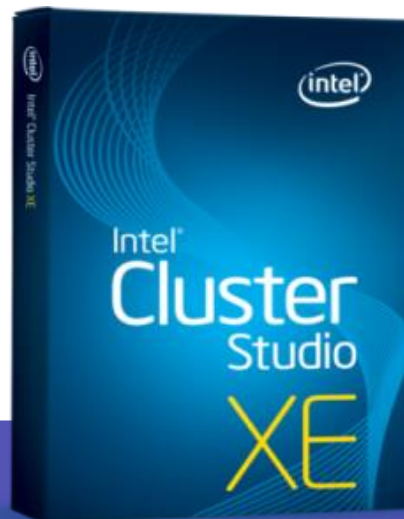
Intel® Inspector XE, Intel® VTune™ Amplifier XE, Intel® Advisor

+ Intel® MPI Library

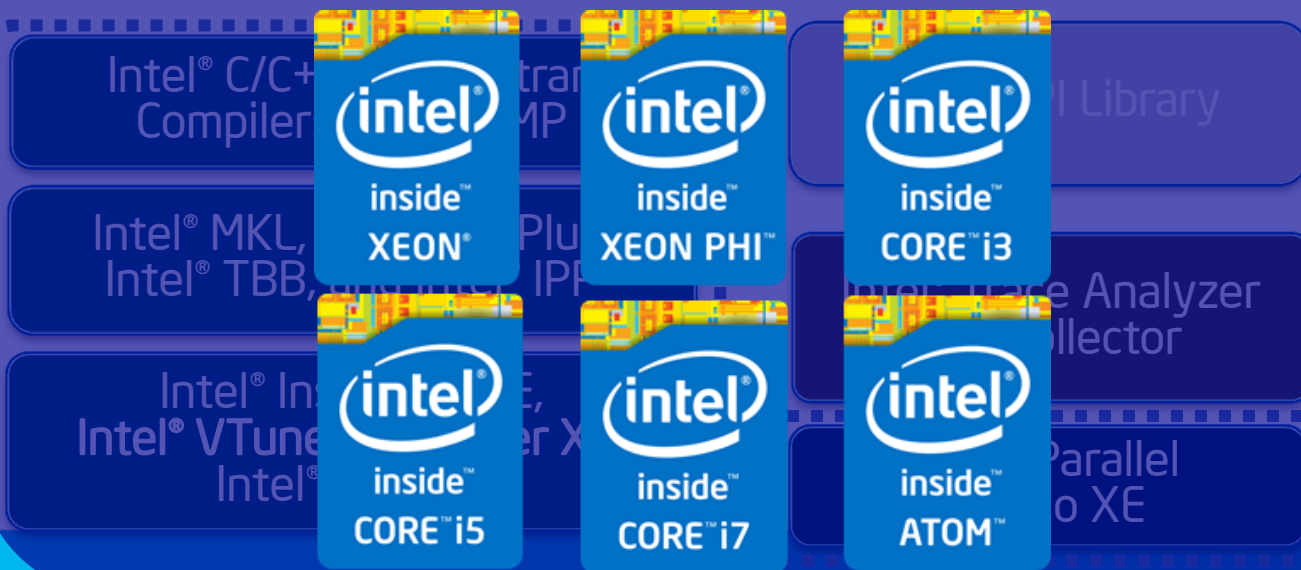
+ Intel® Trace Analyzer and Collector

Intel® Parallel Studio XE

Unifying Intel® Architecture



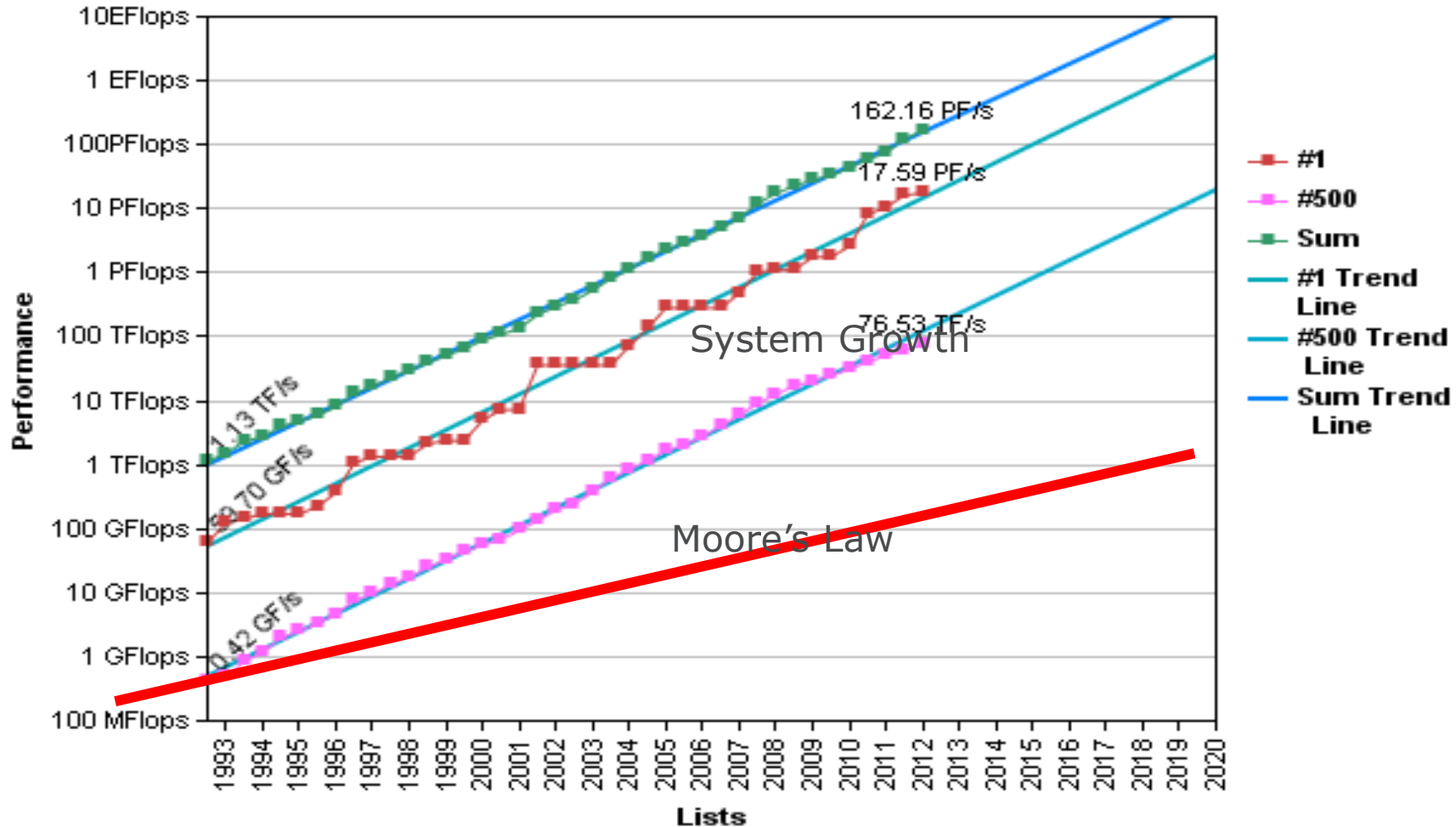
ALL



Technical Trend #1: Top 500 System Performance—Faster than Moore's Law

Future requires heterogeneous computing & high performance fabric

Projected Performance Development



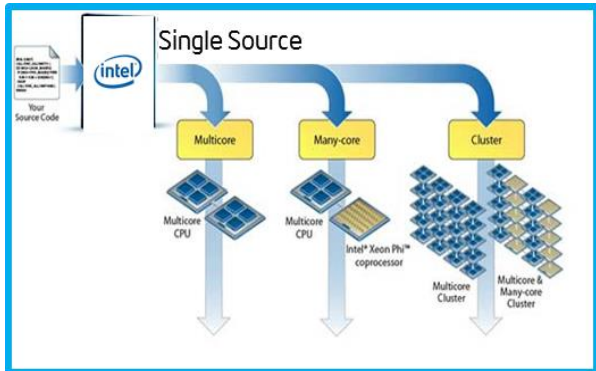
Neo-Heterogeneity at Scale

IDC HPC End-User MCS Study:
Overall Plans For Purchasing Coprocessors



Q: What is your likely accelerator/co-processor purchase plans for your NEXT technical server purchase?

- 78.4% said YES – they plan to purchase coprocessors with their next HPC server
- This is more than double the 29.5% from our 2011 HPC End-User MCS study



IDC Intersect360

Heterogeneity is here to stay - 74% plan to buy...

...but it doesn't have to be HARD

Neo- Heterogeneity = Heterogeneous system with a single programming model

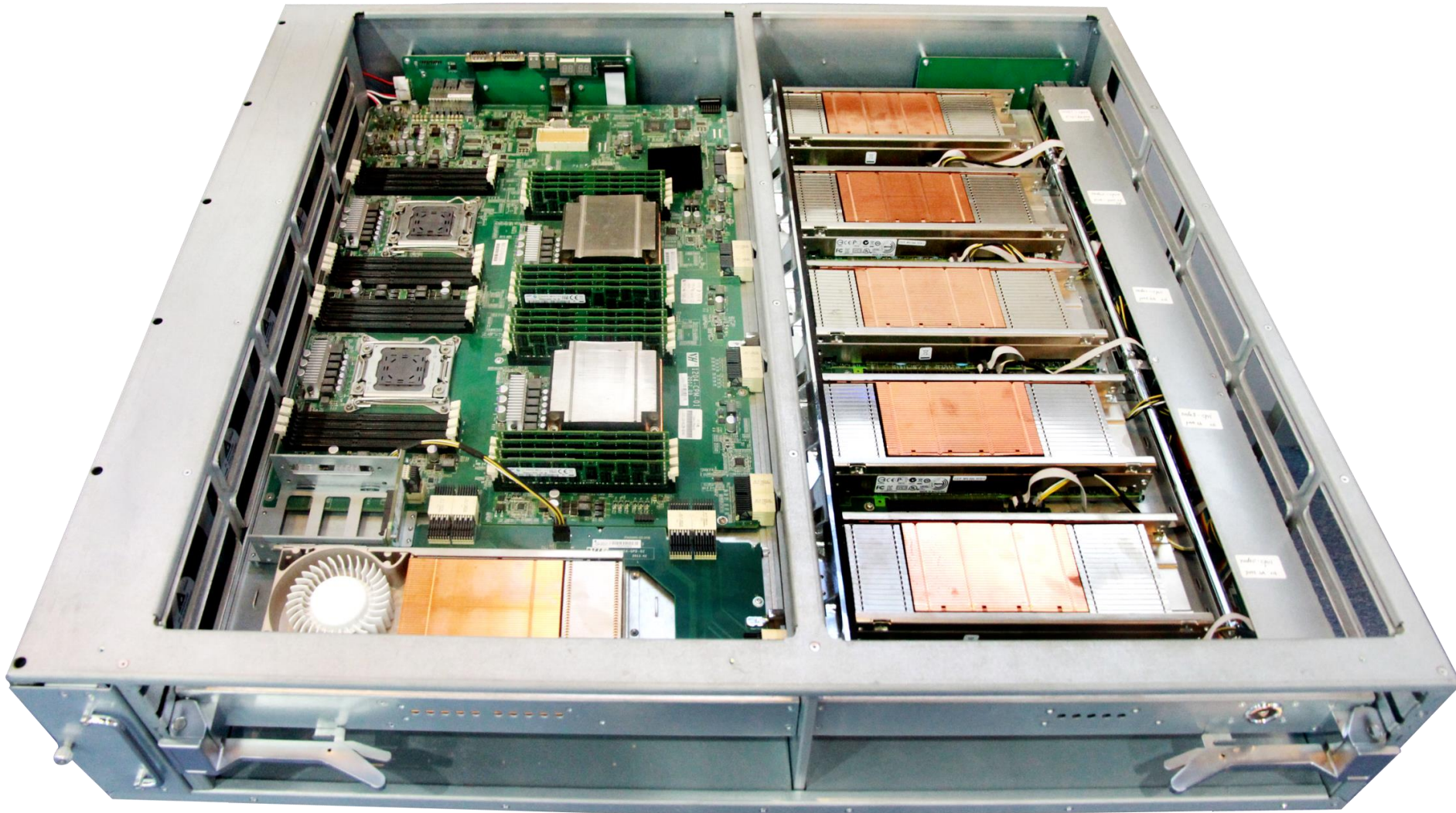
**Multiple Surveys:
Increasing Intel Xeon Phi coprocessor user preference for future buys
and optimizing on Intel Xeon processor in general**

- Source: IDC. 78% surveyed plan to purchase a coprocessor or accelerator, Intersect360
- Source IDC: *Intel Xeon Phi leads all accelerators* in user preference for future buys (Intel 32%, nVidia: 26%)
- IDC and Intersect360 names and brands may be claimed as the property of others.

Milky Way 2 System – New Top500.org #1 System



What it looks like in action



Agenda

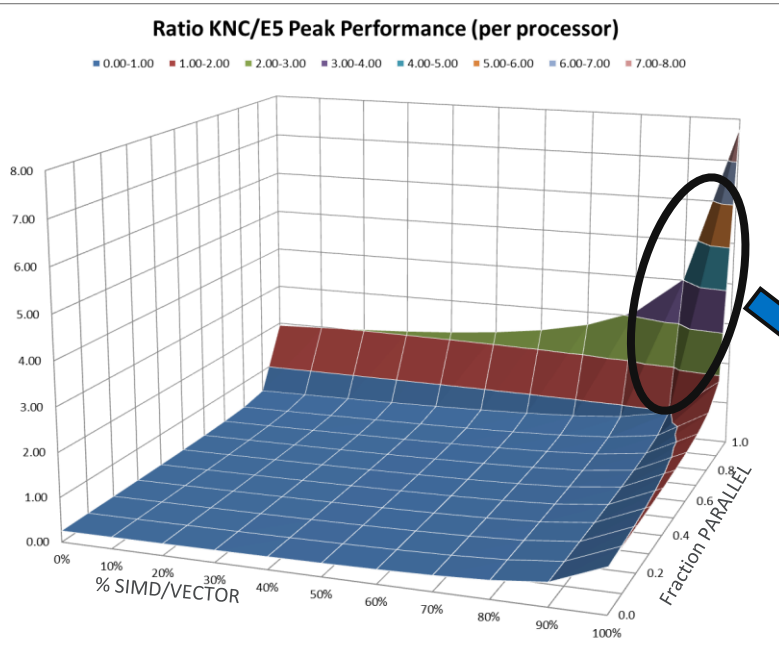
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Intel® Xeon Phi™ Coprocessor: Increases Application Performance up to 10x

Application Performance Examples



KNC= Intel® Xeon Phi™ coprocessor (Knights Corner)
E5 = Intel® Xeon® E5 processor

Customer	Application	Performance Increase ¹ vs. 2S Xeon*
Los Alamos	Molecular Dynamics	Up to 2.52x
Acceleware	8 th order isotropic variable velocity	Up to 2.05x
Jefferson Labs	Lattice QCD	Up to 2.27x
Financial Services	BlackScholes SP Monte Carlo SP	Up to 7x Up to 10.75x
Sinopec	Seismic Imaging	Up to 2.53x ²
Sandia Labs	miniFE (Finite Element Solver)	Up to 2x ³
Intel Labs	Ray Tracing (incoherent rays)	Up to 1.88x ⁴

- Intel® Xeon Phi™ coprocessor accelerates highly parallel & vectorizable applications. (Chart)
- Table provides examples of such applications

Configuration Notes:

1. 2S Xeon vs. 1 Xeon Phi (preproduction HW/SW & Application running 100% on coprocessor unless otherwise noted)
2. 2S Xeon vs. 2S Xeon + 2 Xeon Phi (offload)
3. 8 node cluster, each node with 2S Xeon (comparison is cluster performance with and without 1 Xeon Phi per node) (Hetero)
4. Intel Measured Oct. 2012

Software and workloads used in performance tests may have been optimized for performance only on Intel microprocessors. Performance tests, such as SYSmark* and MobileMark*, are measured using specific computer systems, components, software, operations and functions. Any change to any of those factors may cause the results to vary. You should consult other information and performance tests to assist you in fully evaluating your contemplated purchases, including the performance of that product when combined with other products. Source: Customer Measured results as of October 22, 2012. For more information go to <http://www.intel.com/performance>

DreamWorks Animation Workflow

Improved animation rendering time



Topline
Innovation

Enables artists to preview and evaluate scenes more quickly as changes are made

Lighting modifications are viewed in near real-time instead of rendered overnight

Enables more immediate artist and production collaboration



Bottom-line
Benefits

Reduces design environment complexity by improving workflow

Preserves software development investment while adopting new hardware technologies (i.e. Intel® Xeon Phi™ coprocessors)



Thread Visualization Tool @ Dreamworks

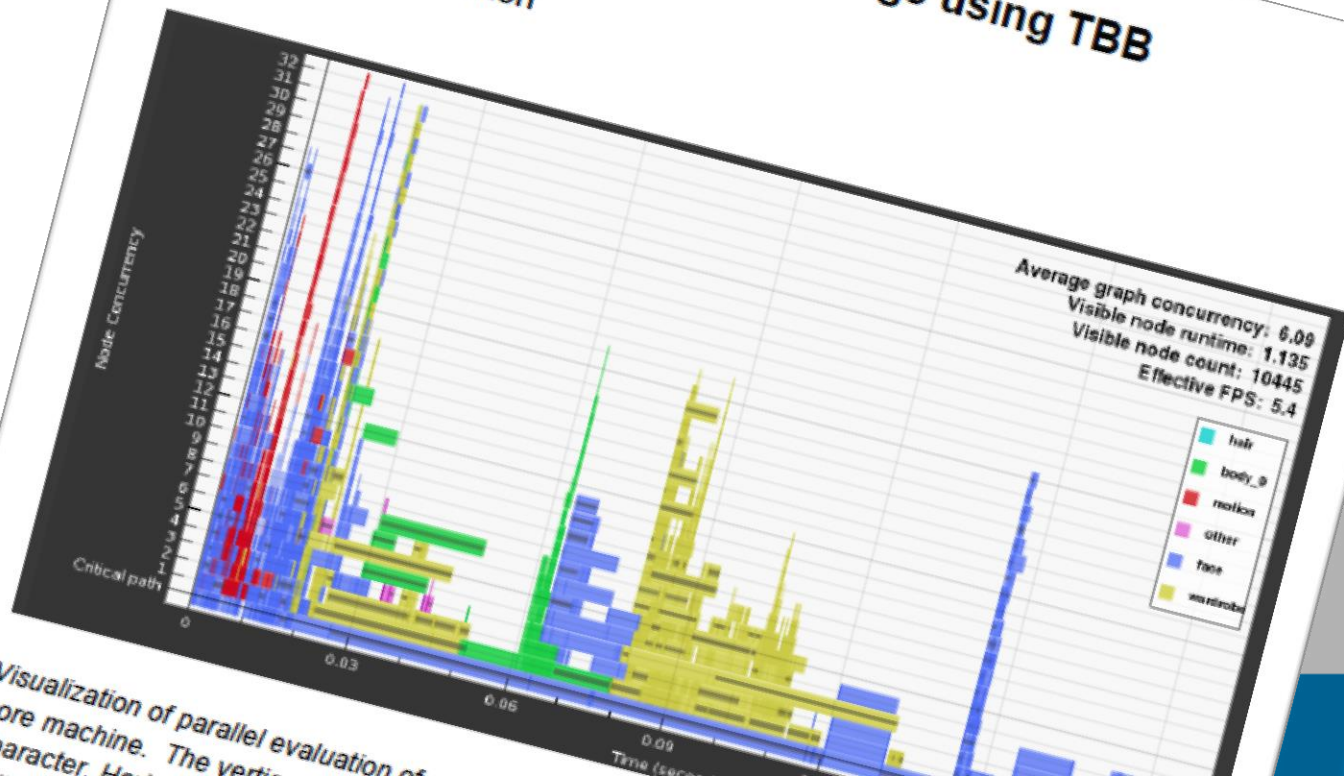
An example of the POWER of PARALLELISM

http://www.multithreadingandvfx.org/course_notes/

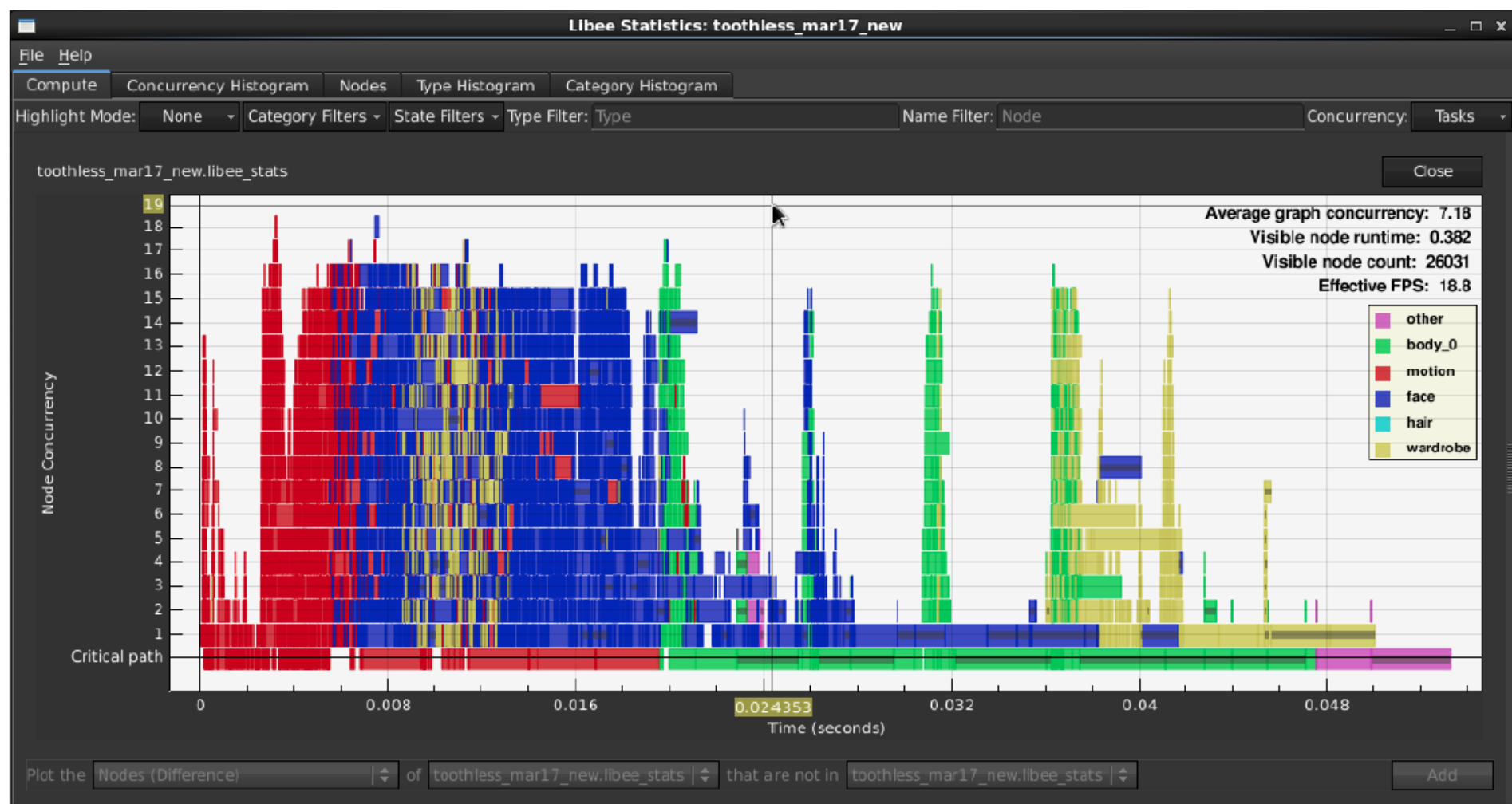
Parallel evaluation of character rigs using TBB

Martin Watt

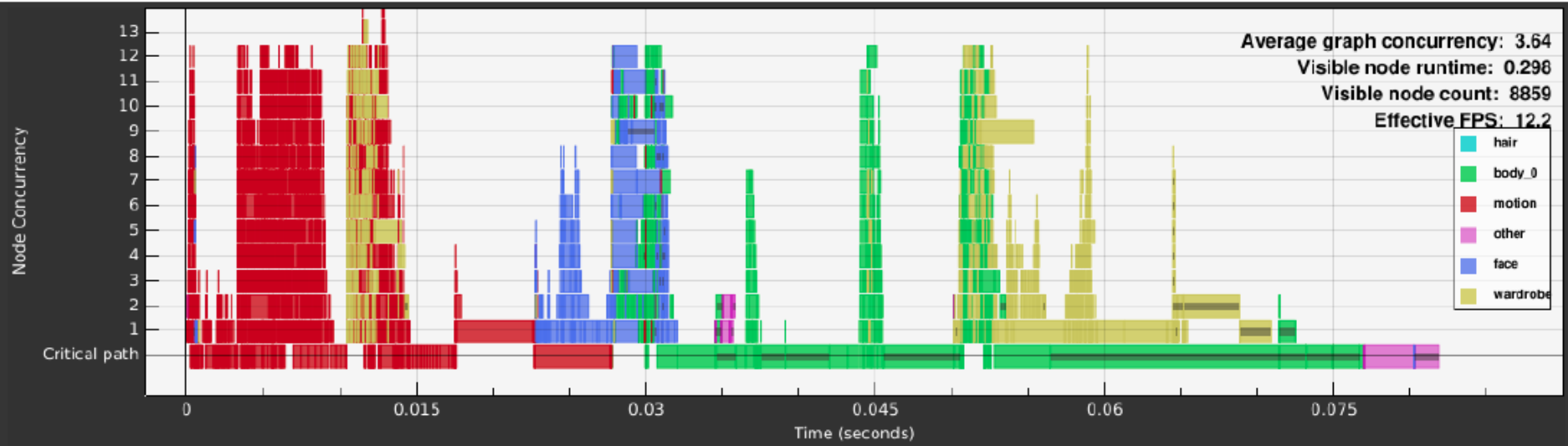
Dreamworks Animation



Visualization of parallel evaluation of core machine. The vertical axis represents the number of nodes being evaluated in parallel. The horizontal axis represents time in seconds. The chart shows the execution of various rig components over time, with the critical path highlighted.

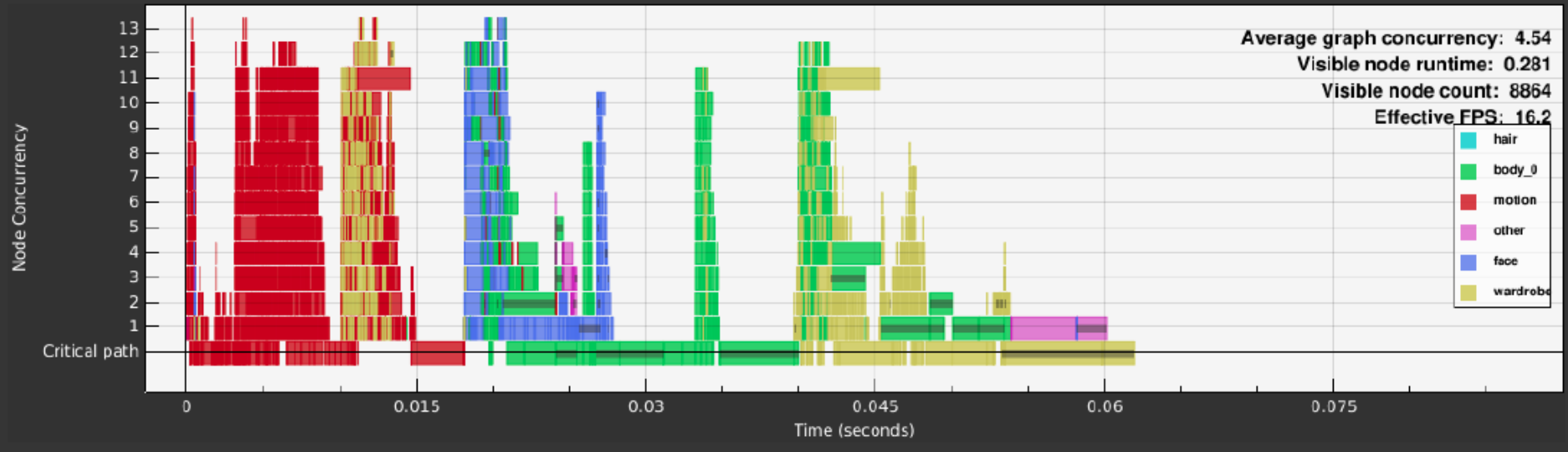


The threading visualization tool enables artists to investigate bottlenecks within the graph. The tool highlights different character rig components in different colors (i.e. body, face, wardrobe, and hair) and provides overall graph concurrency statistics. Note that the average concurrency only represents graph parallelism and does not include node parallelism. The bottom row of nodes are the nodes on the critical path.



/studio/dragon2/shdw_gzimmermann/prod/sqanim/stoothless_walk/libee_stats/frame_152_deform_extras.libee_stats

Close

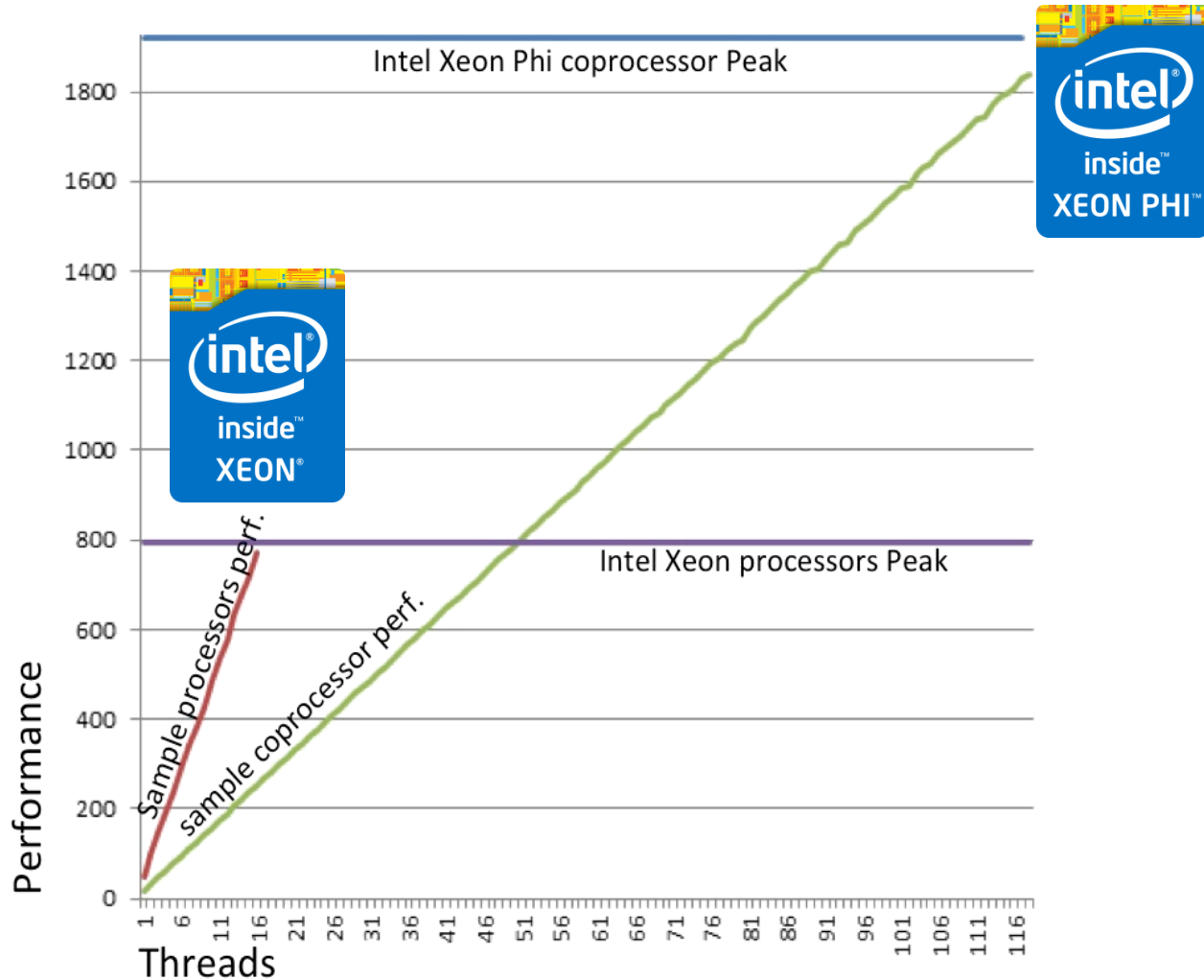


Mode to compare two profiles to check benefits of optimizations



Top graph shows character with motion and deformation system, bottom graph shows addition of clothing. Note that the overall runtime increases only marginally although there is significant extra work being performed in the rig.

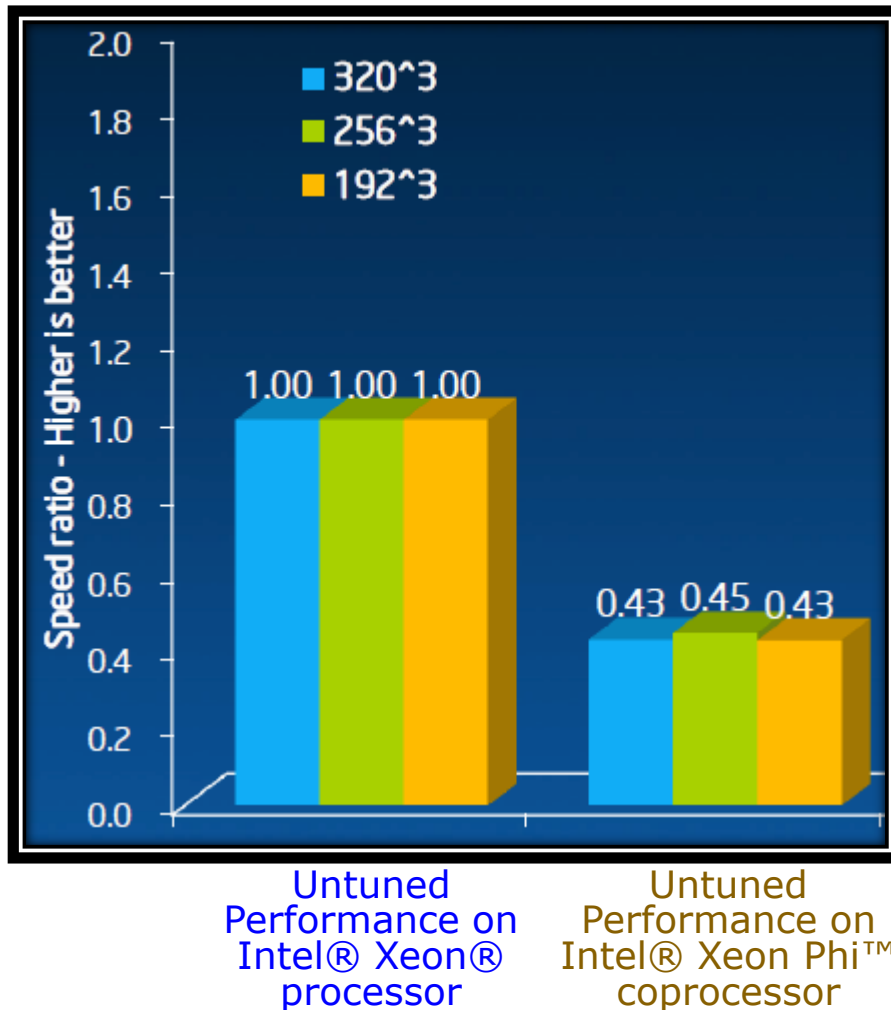
Picture worth many words



Illustrative example

Fortran code using MPI, single threaded originally.

Run on Intel® Xeon Phi™ coprocessor natively (no offload).

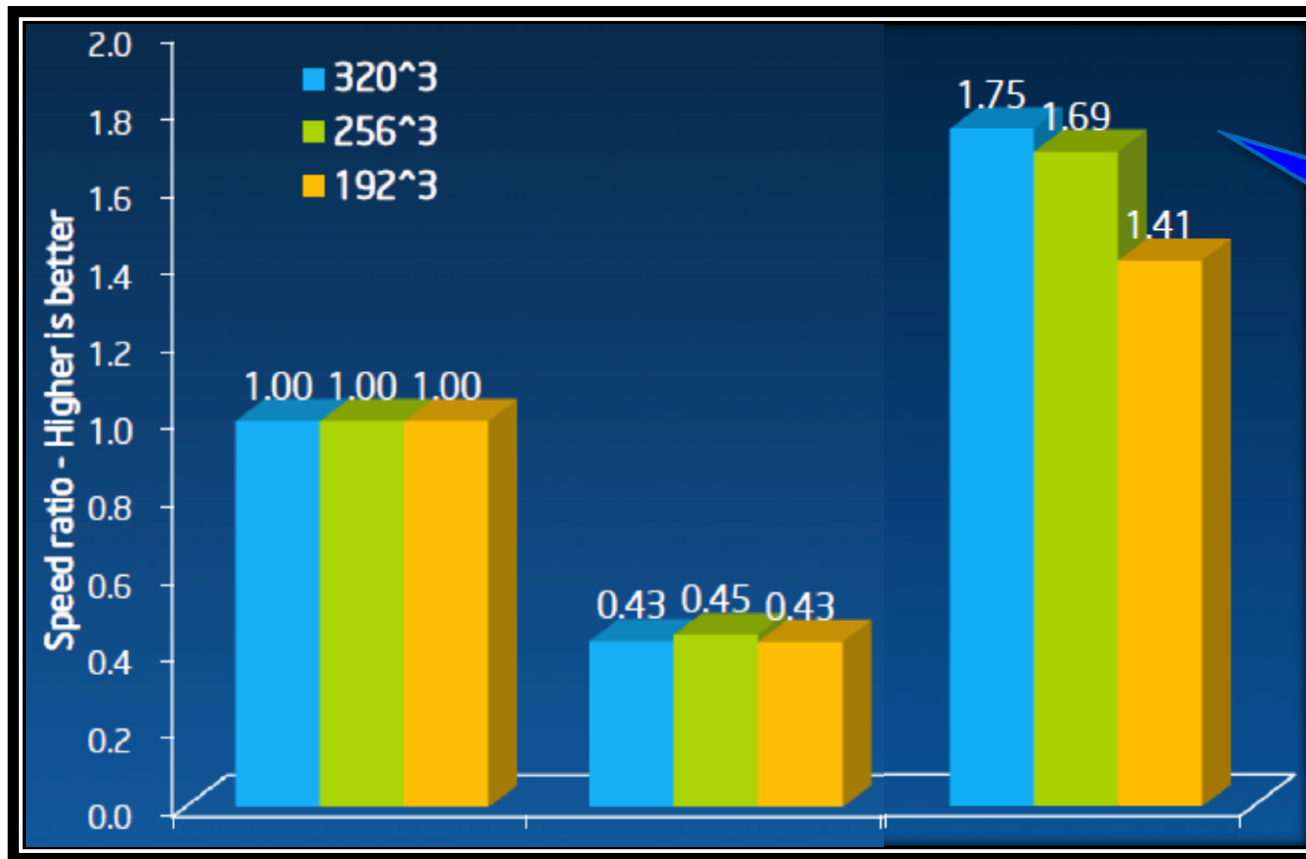


Based on an actual (but confidential) customer example. Shown to illustrate a point about common techniques. Your results may vary!

Illustrative example

Fortran code using MPI, single threaded originally.

Run on Intel® Xeon Phi™ coprocessor natively (no offload).



Untuned Performance on Intel® Xeon® processor

Untuned Performance on Intel® Xeon Phi™ coprocessor

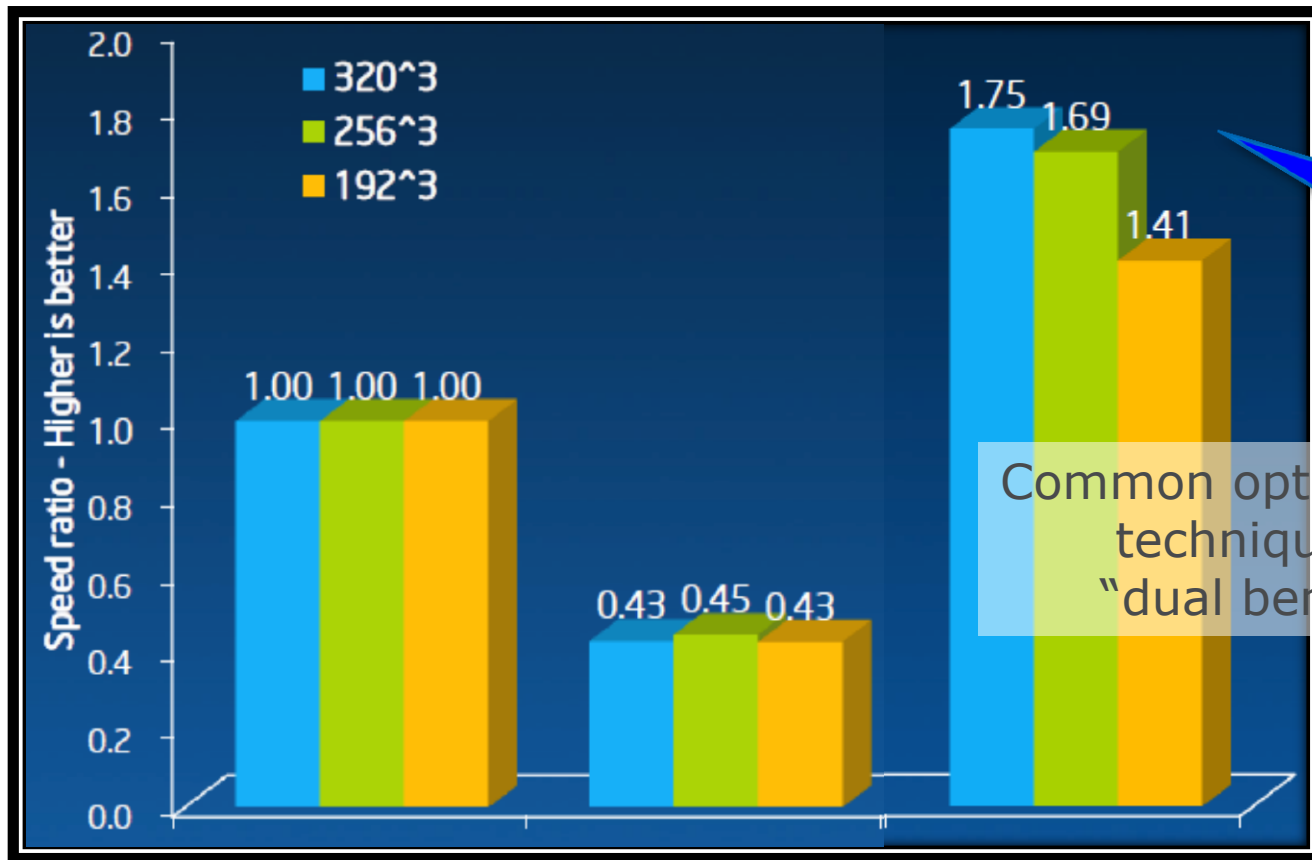
TUNED Performance on Intel® Xeon Phi™ coprocessor

Based on an actual (but confidential) customer example. Shown to illustrate a point about common techniques. Your results may vary!

Illustrative example

Fortran code using MPI, single threaded originally.

Run on Intel® Xeon Phi™ coprocessor natively (no offload).



Yeah!

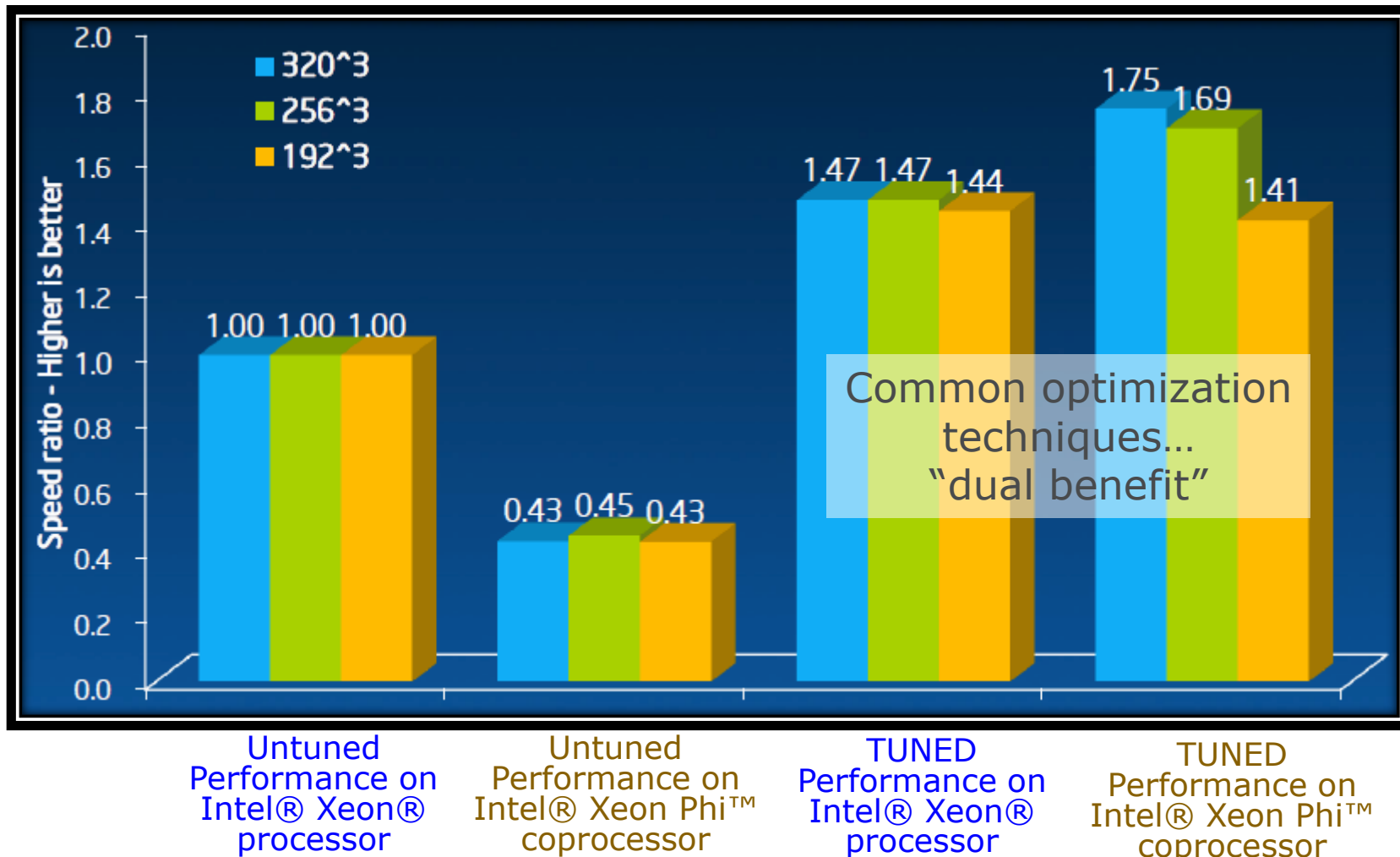
Common optimization techniques... "dual benefit"

Based on an actual (but confidential) customer example. Shown to illustrate a point about common techniques. Your results may vary!

Illustrative example

Fortran code using MPI, single threaded originally.

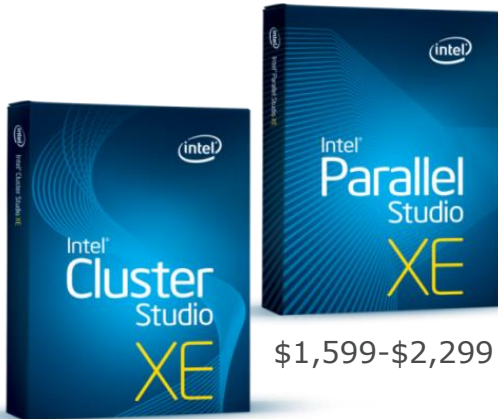
Run on Intel® Xeon Phi™ coprocessor natively (no offload).



Based on an actual (but confidential) customer example. Shown to illustrate a point about common techniques. Your results may vary!

Intel® Parallel Studio XE 2013 SP1 & Intel® Cluster Studio XE 2013 SP1

Faster code + Simplified development



\$2,949

\$1,599-\$2,299

“SP1” release shipping since September 4, 2013

Top New Features

Performance	Analysis Efficiency	Productivity	Cross Platform Portability
<p>Improved compiler and library performance</p> <p>Intel® AVX-512 ready</p> <p>Broadwell & Haswell-EP microarchitecture optimizations</p> <p>Windows* support for Intel® Xeon Phi™ coprocessor</p>	<p>Better data mining for performance tuning</p> <p>Simplified scalability testing for OpenMP*</p> <p>Incremental analysis and easier suppression management</p> <p>Enhanced MPI analysis interface</p>	<p>Improved conditional numerical reproducibility</p> <p>Enhanced GDB for Linux* and OS X*</p>	<p>OpenMP* 4.0 SIMD and target constructs</p> <p>Expanded C++11</p> <p>Expanded Fortran 2003 & 2008</p> <p>Improved MPI Performance and Scalability</p>

More info at: <http://intel.ly/perf-tools>

Optimization Framework

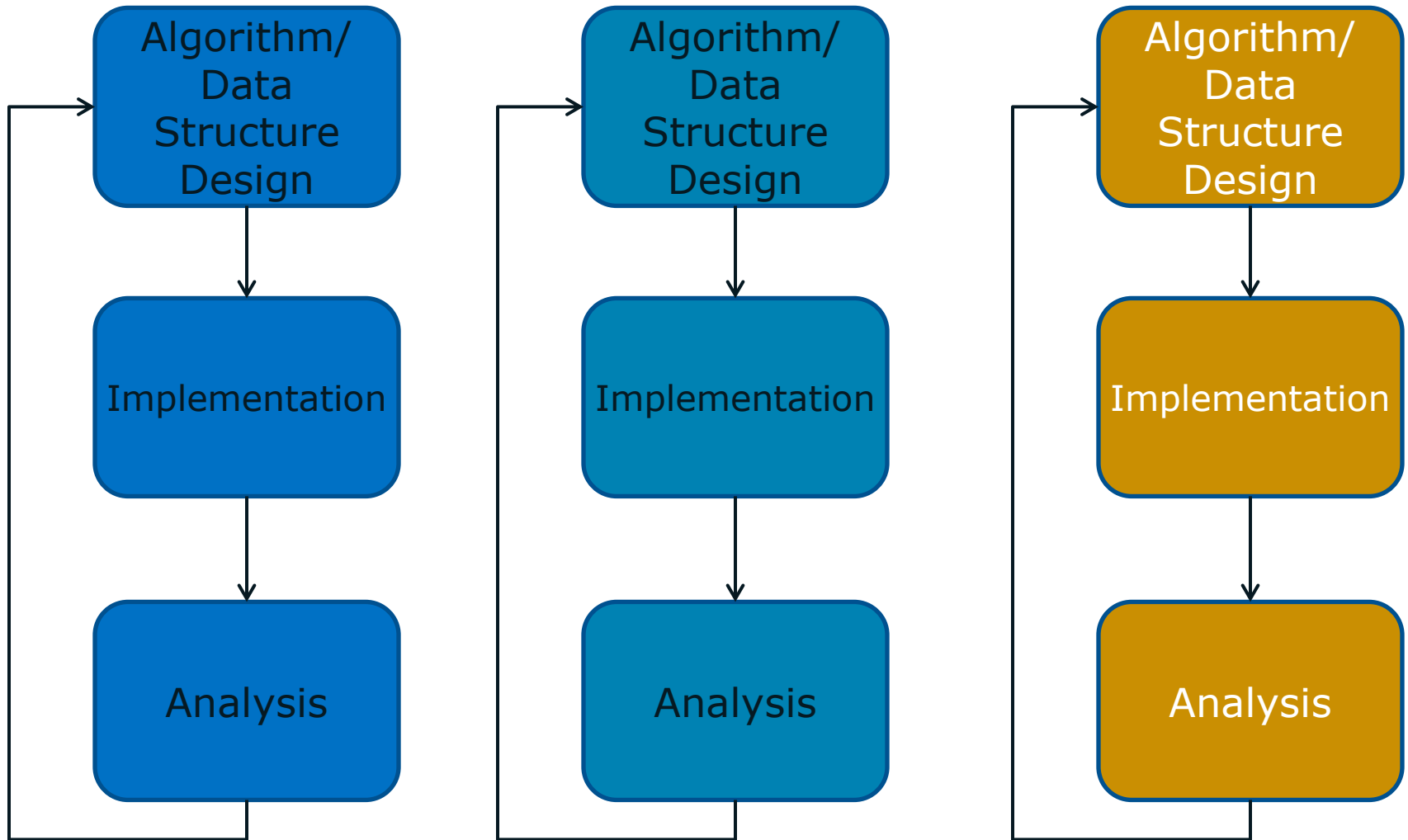
Scalar



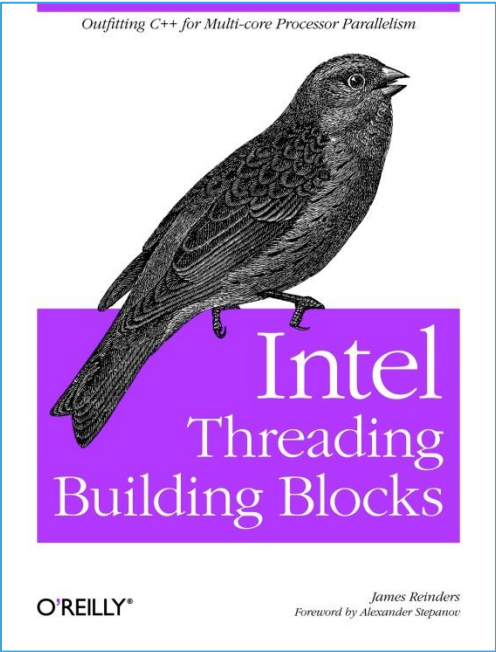
Vector



Parallel



www.threadingbuildingblocks.org



- ✓ **Most popular C++ abstraction**
- ✓ **Windows***
- ✓ **Linux***
- ✓ **OS* X**
- ✓ **Xbox 360**
- ✓ **Solaris***
- ✓ **FreeBSD***
- ✓ **Intel processors**
- ✓ **AMD processors**
- ✓ **SPARC processors**
- ✓ **IBM processors**
- ✓ **open source**
- ✓ **standard committee submissions**



The most used method to parallelize C++ programs

* Other names and brands may be claimed as the property of others.

Learn more about this book:

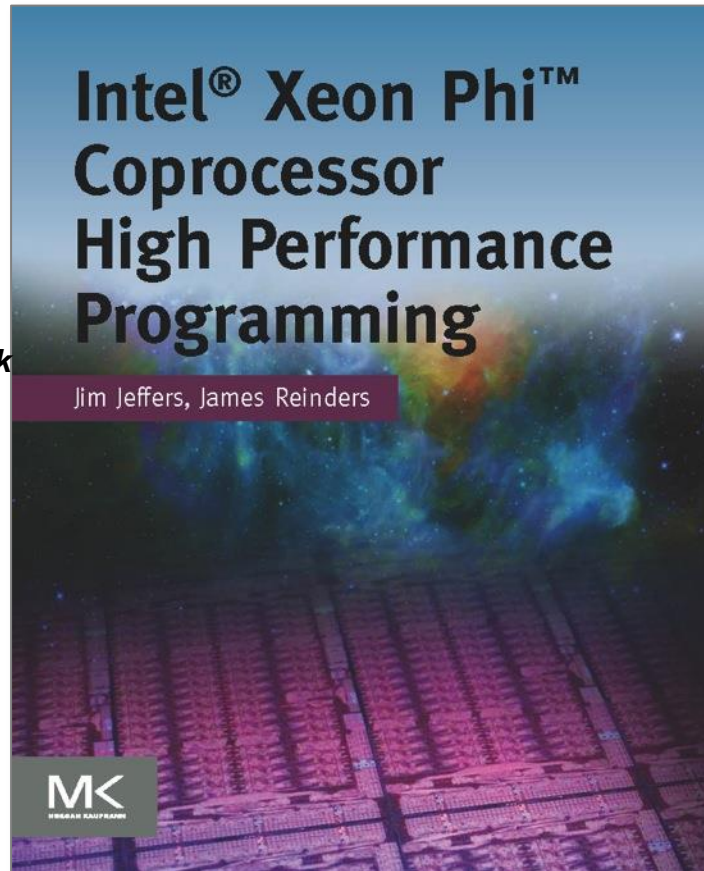
lotsofcores.com

**It all comes down to
PARALLEL
PROGRAMMING !
(applicable to processors
and Intel® Xeon Phi™
coprocessors both)**

Forward, Preface

Chapters:

- 1. Introduction*
 - 2. High Performance Closed Track
Test Drive!*
 - 3. A Friendly Country Road Race*
 - 4. Driving Around Town:
Optimizing A Real-World
Code Example*
 - 5. Lots of Data (Vectors)*
 - 6. Lots of Tasks (not Threads)*
 - 7. Offload*
 - 8. Coprocessor Architecture*
 - 9. Coprocessor System Software*
 - 10. Linux on the Coprocessor*
 - 11. Math Library*
 - 12. MPI*
 - 13. Profiling and Timing*
 - 14. Summary*
- Glossary, Index*



Available since February 2013.

This book belongs on the bookshelf of every HPC professional. Not only does it successfully and accessibly teach us how to use and obtain high performance on the Intel MIC architecture, it is about much more than that. It takes us back to the universal fundamentals of high-performance computing including how to think and reason about the performance of algorithms mapped to modern architectures, and it puts into your hands powerful tools that will be useful for years to come.

**—Robert J. Harrison
Institute for Advanced
Computational Science,
Stony Brook University**

**Intel® Xeon Phi™ Coprocessor High Performance Programming,
Jim Jeffers, James Reinders, (c) 2013, publisher: Morgan Kaufmann**

Learn more about this book:
parallelbook.com

**SC'13 tutorial
November 2013
In Denver**

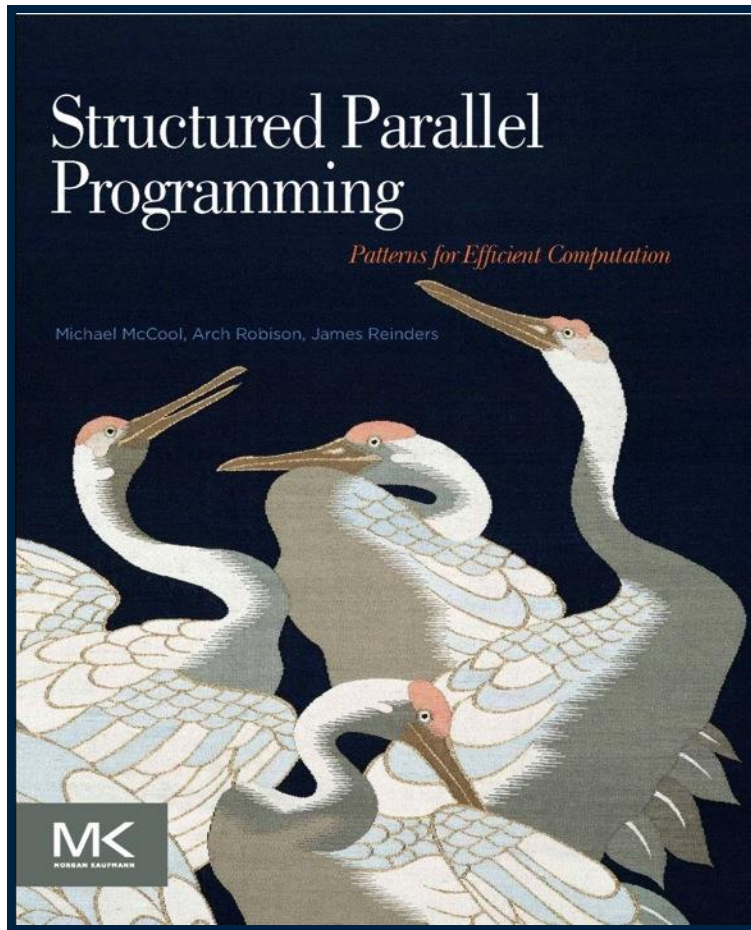
Teaches parallel programming using a new pattern-based approach.

Extensive examples in Cilk Plus and TBB.

Not about any specific hardware, but relevant to all.

It's about effective parallel programming.

Great for teaching!



Available since July 2012.

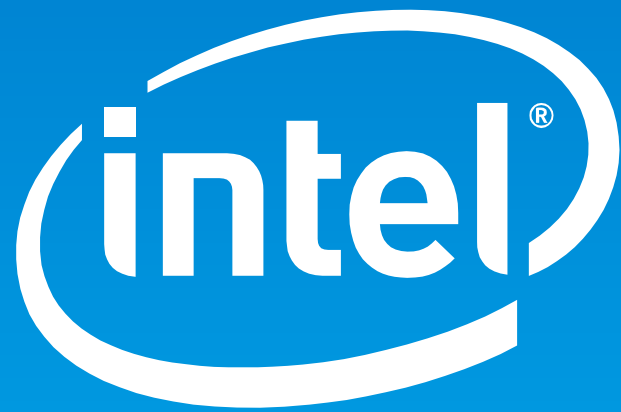
This is a really great book...

I've been dreaming for a while of a modern accessible book that I could recommend to my threading-deprived colleagues and assorted enquirers to get them up to speed with the core concepts of multithreading as well as something that covers all the major current interesting implementations.

Finally I have that book.

**—Martin Watt,
Principal Engineer,
Dreamworks Animation**

**Structured Parallel Programming, Michael McCool, Arch Robison, James Reinders
(c) 2012, publisher: Morgan Kaufmann**



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